

6. A semiconductor physical quantity sensor comprising:
a semiconductor chip placed on at least one of a resin case and a substrate via a pedestal, and
wherein both first pads in said semiconductor chip which are to be pulled down and a ground pad are
electrically connected to a ground outside said semiconductor chip.

7. The semiconductor physical quantity sensor according to Claim 6, wherein characterized in that both
second pads in said semiconductor chip which are to be pulled up and a power supply pad are electrically
connected to a power supply outside said semiconductor chip

8. A semiconductor physical quantity sensor comprising:
a semiconductor chip placed on at least one of a resin case and a substrate via a pedestal, and
wherein both second pads in said semiconductor chip which are to be pulled up and a power supply pad
are electrically connected to a power supply outside said semiconductor chip.

9. A semiconductor physical quantity sensor comprising:
a semiconductor chip placed on a resin case via a pedestal, said resin case including lead frames that are
insert-molded, and within said resin case are formed both a ground-connecting external wire through which a
ground pad of said semiconductor chip and first pads to be pulled down are electrically connected, and an
power-supply-connecting external wires through which a power supply pad of said semiconductor chip and
second pads to be pulled up are electrically connected;
wherein said ground-connecting external wire is connected to a ground lead frame, whereas said
power-supply-connecting external wire is connected to a power supply lead frame.

10. The semiconductor physical quantity sensor according to Claim 9, wherein said ground-connecting
external wire and said power-supply-connecting external wire are each connected to corresponding lead frames
outside said resin case

11. The semiconductor physical quantity sensor according to Claims 9 to 10, wherein said